



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	ISC010N04NM6	<b>Issued</b>	11. August 2021
<b>MA#</b>	MA005402073		
<b>Package</b>	PG-TDSON-8-36	<b>Weight*</b>	115.50 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.515	1.31	1.31	13115	13115
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		135	
	non noble metal	iron	7439-89-6	0.052	0.04		449	
	non noble metal	copper	7440-50-8	51.740	44.82	44.87	447985	448569
wire	noble metal	gold	7440-57-5	0.044	0.04	0.04	380	380
encapsulation	organic material	carbon black	1333-86-4	0.081	0.07		700	
	plastics	epoxy resin	-	6.387	5.53		55304	
	inorganic material	silicondioxide	60676-86-0	33.958	29.40	35.00	294020	350024
leadfinish	non noble metal	tin	7440-31-5	1.392	1.20	1.20	12048	12048
plating	noble metal	silver	7440-22-4	0.194	0.17	0.17	1678	1678
solder	non noble metal	tin	7440-31-5	0.038	0.03		330	
	noble metal	silver	7440-22-4	0.048	0.04		412	
	non noble metal	lead	7439-92-1	1.819	1.58	1.65	15750	16492
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.01		149	
	non noble metal	copper	7440-50-8	17.131	14.83	14.84	148330	148524
clip plating	noble metal	silver	7440-22-4	1.059	0.92	0.92	9170	9170
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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